

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

Gormley et al.

GROUP:

2822

SERIAL NO:

10/617,427

EXAMINER: P.E. Perkins

FILED:

July 11, 2003

FOR:

A METHOD FOR FORMING A MICRO-MECHANICAL COMPONENT IN A SEMICONDUCTOR WAFER, AND A SEMICONDUCTOR WAFER COMPRISING A MICRO-MECHANICAL COMPONENT FORMED THEREIN

Mail Stop Amendment Commissioner of Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

AMENDMENT

In response to the Office Action mailed February 7, 2005, please amend the aboveidentified application as indicated on the attached sheets.